

HQDFM Design for Manufacture(DFM) Report

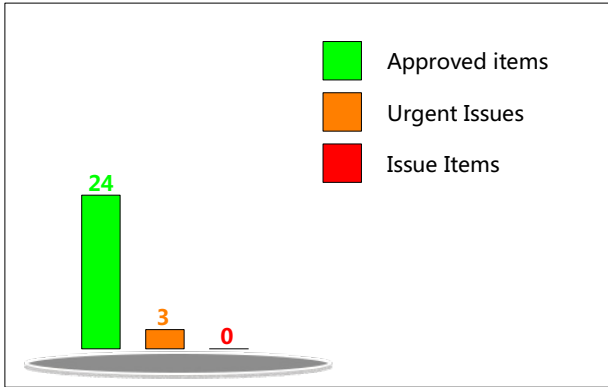
File name: 0000A545217_1

Time: 2025-09-28 Layer count:2

PCB Thickness: 1.60

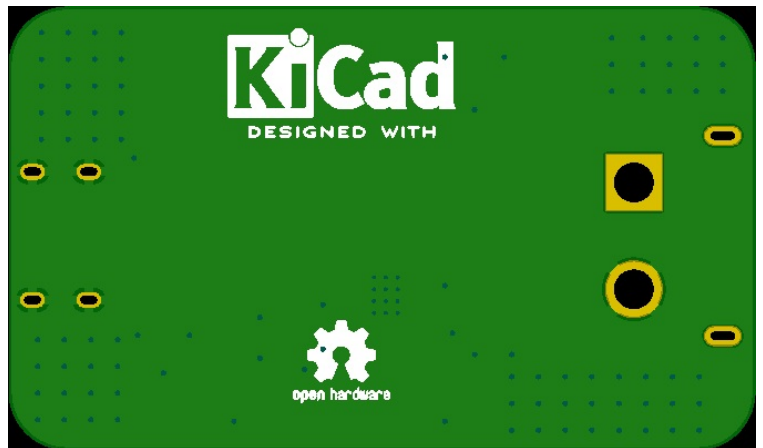
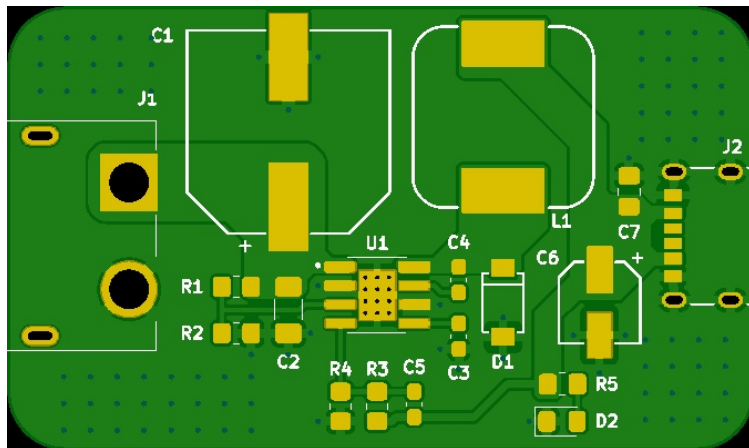
Quantity: 5

mm

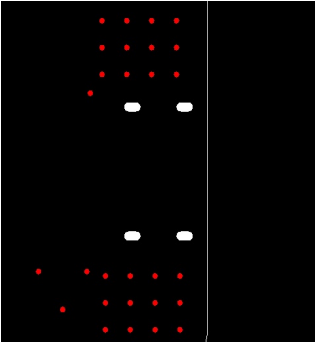
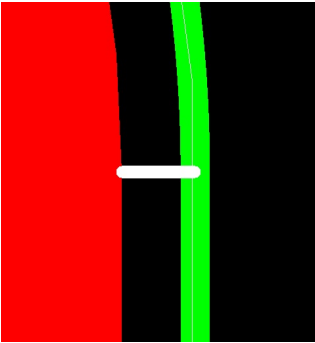


Basic Board Specs	Trace Width/Spacing	10.00/8.00mil+
	Milling Density	106.3175m/m ²
	Surface Finish Area	17.06%
	Test Point Count	53

The file size is small, which can affect the surface mount assembly process. It is recommended to have a size larger than 7*7cm. You can optimize the size by adding a process edge or increasing the panelization.



Type	Category	No. of Checks	Result
PCB Trace Analysis	Smallest Trace Width	1	Pass
	Smallest Trace Spacing	3	Pass 53
	SMD Pad Spacing	2	Pass 11
	Pad Size	3	Pass 5
	Hatched Copper Pour	2	Pass
	Annular Ring Size	2	Pass 2
	Drill to Copper	5	Pass 15
	Signal Integrity	4	Pass
	Copper-to-Board Edge	2	Fail 16
	Holes on SMD Pads	4	Pass
	Open/Shorts (IPC)	1	Fail
PCB Drilling Analysis	Drill Diameter	8	Pass 32 , Fail 2
	Drill Hole Density	1	Pass
	Drill Diameter	8	Pass 32 , Fail 2
	Drill Spacing	4	Pass
	Drill to Board Edge	4	Pass
	Drill Hole Density	1	Pass
	Special Drill Holes	2	Pass
PCB Solder Mask Analysis	Solder Mask Dam	2	Pass 13
	Missing SMask Opening	1	Pass
PCB Silk Analysis	Silkscreen Spacing	1	Pass
PCBA Fiducial Analysis	Fiducial Count	1	Pass

ID	Check	Limits	Value	Issue	Image	Position	Qty	Level
1	Drill Diameter_Slot Aspect Ratio	1.5,2,2	0.30 mm	Slots with aspect ratio of 2.00 were detected in your design. This could increase the risk of incomplete drilling of the slot, which decrease manufacturing efficiency and yield, and affect the reliability of the boards. The ratio should be increased to at least 2:1		160.95,-110.00	4	Warning
2	Copper-to-Board Edge_Copper-to-Board Edge	8,15,20	0.25 mm	Copper-to-edge spacing of 9.86mil was detected in your design.This could increase the risk of exposed copper on the edge of the boards or damaged traces/pads, which decrease manufacturing efficiency and yield, and affect the reliability of the boards. It is recommended to increase the spacing to at least 0.4 mm for edge routing and for v-cuts (v-cut spacing may depends on board thickness).		164.37,-98.50	8	Warning